

1. General description

WeEn Gen-2 Silicon Carbide MOSFET in a TO247-4L plastic package, designed for high frequency, high efficiency systems.



AEC - Q101 Qualified



2. Features and benefits

- Kelvin source configuration
- Low specific on-resistance
- Optimized dynamic performance
- 0V turn-off V_{GS} for simple gate driving
- 100% UIS Tested
- Easy to parallel
- RoHS compliant
- Automotive Qualified (AEC-Q101)

3. Applications

- Automotive on board chargers
- Automotive DC-DC converters
- Automotive electric compressor motor drives
- HV battery management systems

4. Quick reference data

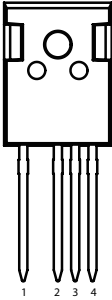
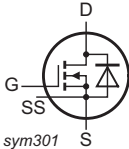
Table 1. Quick reference data

Table 17: Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V _{DS}	drain-source voltage	25 °C ≤ T _j ≤ 175 °C		750			V
I _D	drain current	V _{GS} = 18 V; T _{mb} = 25 °C		54			A
P _{tot}	total power dissipation	T _{mb} = 25 °C, T _j = 175 °C		231			W
T _j	junction temperature			-55 to 175			°C
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
R _{DS(on)}	drain-source on-state resistance	V _{GS} = 15 V; I _D = 15 A; T _j = 25 °C		-	71.5	-	mΩ
		V _{GS} = 18 V; I _D = 15 A; T _j = 25 °C		-	55	72	mΩ
Dynamic characteristics							
Q _{G(tot)}	total gate charge	I _D = 15 A; V _{DS} = 400 V; V _{GS} = -4 V/18 V; T _j = 25 °C		-	53	-	nC
Q _{GD}	gate-drain charge			-	7.3	-	nC
Source-drain diode							
Q _r	recovered charge	I _{SD} = 15 A; di/dt = 500 A/μs; V _{DS} = 400 V; T _j = 25 °C		-	58.6	-	nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	D	drain		
2	S	source		
3	SS	source sense		
4	G	gate		
mb	D	mounting base; connected to drain		

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC2M70075R-A	TO247-4L	WNSC2M70075R-A6Q	Tube	30	TO247N-4L	17-Dec-2021

7. Marking

Table 4. Marking codes

Type number	Marking codes
WNSC2M70075R-A	WNSC2M 70075R-A

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{DS}	drain-source voltage	$25\text{ }^{\circ}\text{C} \leq T_j \leq 175\text{ }^{\circ}\text{C}$		750	V
$V_{GS,max}$	gate-source voltage	Absolute maximum values		-10 to 22	V
$V_{GS,op}$	gate-source voltage	Recommended operational values		-4 to 18	V
P_{tot}	total power dissipation	$T_{mb} = 25\text{ }^{\circ}\text{C}$; $T_j = 175\text{ }^{\circ}\text{C}$		231	W
I_D	drain current	$V_{GS} = 18\text{ V}$; $T_{mb} = 25\text{ }^{\circ}\text{C}$		54	A
		$V_{GS} = 18\text{ V}$; $T_{mb} = 100\text{ }^{\circ}\text{C}$		38	A
I_{DM}	peak drain current	pulse width t_p limited by T_{jmax}	Fig.17	108	A
I_S	continuous diode current	$V_{GS} = -4\text{ V}$; $T_{mb} = 25\text{ }^{\circ}\text{C}$		41	A
I_{SM}	pulse diode current	$V_{GS} = -4\text{ V}$; pulse width t_p limited by T_{jmax}		108	A
E_{as}	single pulse drain-to-source avalanche	$I_{AS} = 17.2\text{ A}$; $L = 1\text{ mH}$; $V_{DD} = 100\text{ V}$; $T_j = 25\text{ }^{\circ}\text{C}$		147	mJ
T_{stg}	storage temperature			-55 to 175	$^{\circ}\text{C}$
T_j	junction temperature			-55 to 175	$^{\circ}\text{C}$
$T_{sld(M)}$	peak soldering temperature			260	$^{\circ}\text{C}$

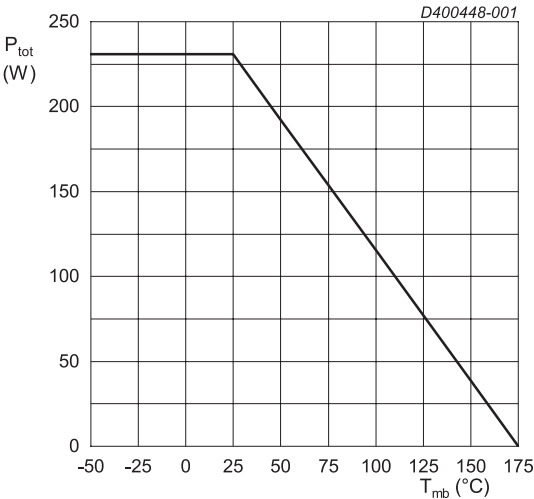


Fig. 1. Total power dissipation as a function of mounting base temperature; maximum values

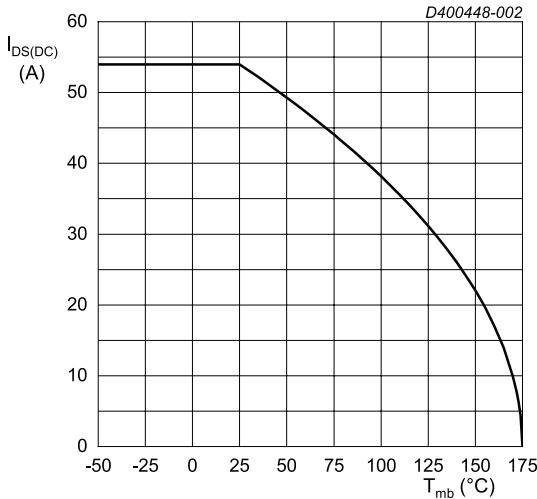


Fig. 2. Continuous Drain Current as a function of mounting base temperature

9. Thermal & Mechanical characteristics

Table 6. Thermal & Mechanical characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base			-	0.65	-	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air		-	40	-	K/W
M_d	Mounting torque	M3 or 6 - 32 screw		-	-	0.6	Nm

Note: It is recommended that a metal washer is inserted between screw head and mounting tab.
Do not use self-tapping screws.
Device is ESD sensitive. Handling precautions are recommended.

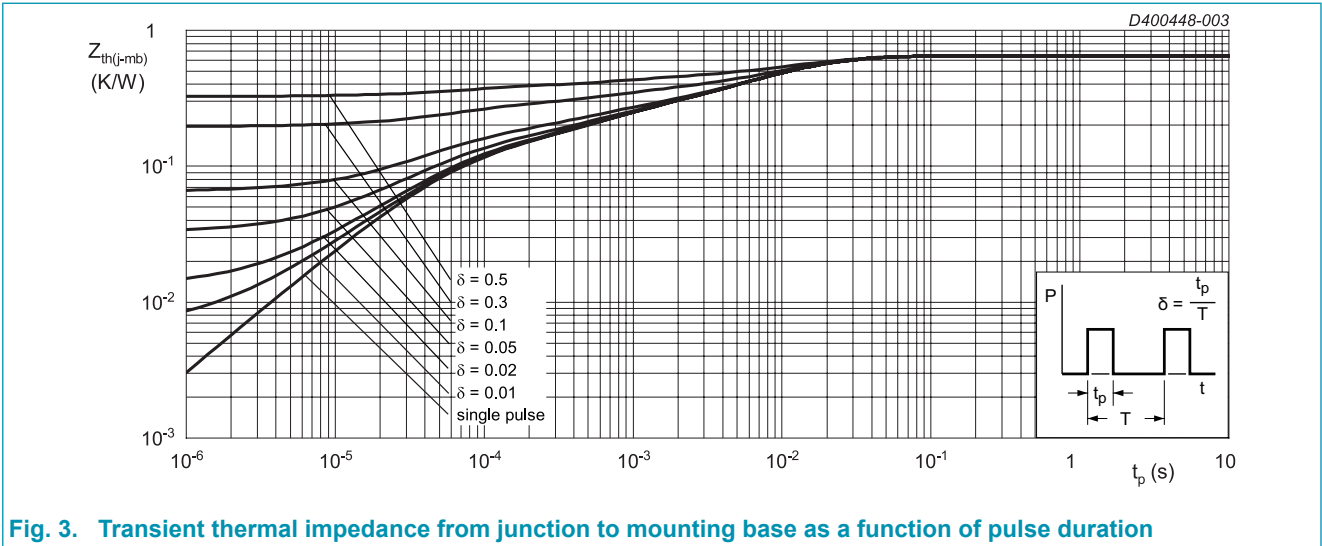
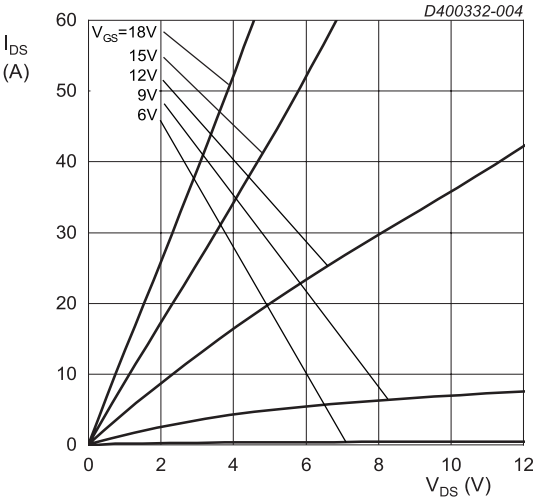


Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse duration

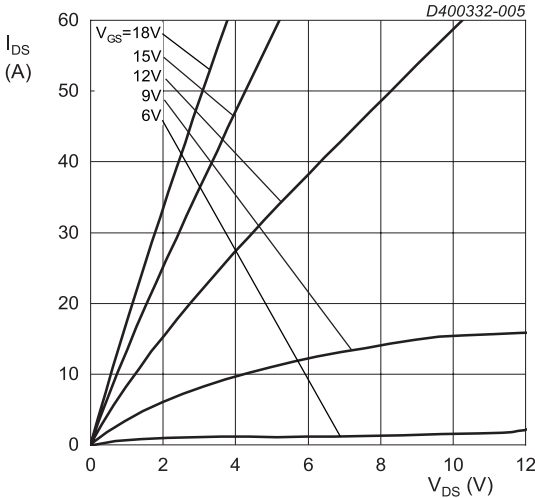
10. Characteristics

Table 7. Characteristics

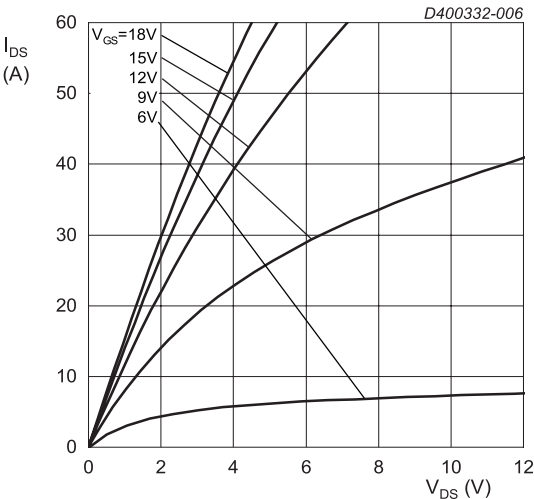
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V _{(BR)DSS}	drain-source breakdown voltage	I _D = 100 μA; V _{GS} = 0 V; T _J = 25 °C		750	-	-	V
V _{GS(th)}	gate-source threshold voltage	I _D = 4 mA; V _{DS} = V _{GS} ; T _J = 25 °C		2	2.8	3.6	V
		I _D = 4 mA; V _{DS} = V _{GS} ; T _J = 175 °C		-	2.1	-	V
I _{DSS}	drain leakage current	V _{DS} = 750 V; V _{GS} = 0 V; T _J = 25 °C		-	0.1	50	μA
		V _{DS} = 750 V; V _{GS} = 0 V; T _J = 175 °C		-	5	-	μA
I _{GSS}	gate leakage current	V _{GS} = 22 V; V _{DS} = 0 V; T _J = 25 °C		-	5	100	nA
		V _{GS} = -10 V; V _{DS} = 0 V; T _J = 25 °C		-	5	100	nA
R _{DS(on)}	drain-source on-state resistance	V _{GS} = 15 V; I _D = 15 A; T _J = 25 °C		-	71.5	-	mΩ
		V _{GS} = 18 V; I _D = 15 A; T _J = 25 °C		-	55	72	mΩ
		V _{GS} = 18 V; I _D = 15 A; T _J = 175 °C		-	66	-	mΩ
R _G	gate resistance	f = 1 MHz; T _J = 25 °C		-	1.36	-	Ω
g _{fs}	transconductance	V _{DS} = 20 V; I _D = 15 A; T _J = 25 °C		-	10	-	S
Dynamic characteristics							
Q _{G(tot)}	total gate charge	I _D = 15 A; V _{DS} = 400 V; V _{GS} = -4 V/18 V; T _J = 25 °C		-	53	-	nC
Q _{GS}	gate-source charge			-	22	-	nC
Q _{GD}	gate-drain charge			-	7.3	-	nC
C _{iss}	input capacitance	V _{DS} = 400 V; V _{GS} = 0 V; f = 1 MHz; T _J = 25 °C		-	1217	-	pF
C _{oss}	output capacitance			-	98	-	pF
C _{rss}	reverse transfer capacitance			-	8	-	pF
E _{oss}	Coss stored energy			-	7.8	-	μJ
t _{d(on)}	turn-on delay time	V _{DS} = 400 V; V _{GS} = -4 V/18 V; R _{G(ext)} = 5.1 Ω; I _D = 7.5 A; L = 100 μH; T _J = 25 °C		-	20	-	ns
t _r	rise time			-	15	-	ns
t _{d(off)}	turn-off delay time			-	34	-	ns
t _f	fall time			-	13	-	ns
E _{on}	turn-on energy (SiC Diode FWD)		Fig.19	-	53	-	μJ
E _{off}	turn-off energy (SiC Diode FWD)		Fig.19	-	10	-	μJ
E _{on}	turn-on energy (Body Diode FWD)		Fig.19	-	67	-	μJ
E _{off}	turn-off energy (Body Diode FWD)		Fig.19	-	9	-	μJ
Source-drain diode							
V _{SD}	source-drain voltage	V _{GS} = 0 V; I _{SD} = 15 A; T _J = 25 °C		-	3.7	-	V
		V _{GS} = -4 V; I _{SD} = 15 A; T _J = 25 °C		-	4.2	-	V
		V _{GS} = -4 V; I _{SD} = 15 A; T _J = 175 °C		-	3.7	-	V
t _{rr}	reverse recovery time	I _{SD} = 15 A; di/dt = 500 A/μs; V _{DS} = 400 V; T _J = 25 °C		-	25.3	-	ns
Q _r	recovered charge			-	58.6	-	nC
I _{rrm}	reverse recovery current			-	4.6	-	A



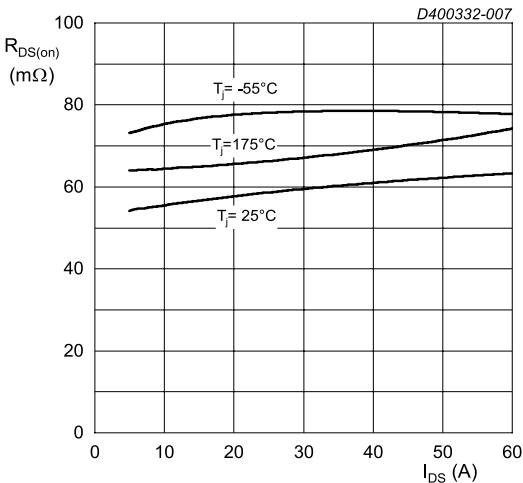
$T_j = -55\text{ }^{\circ}\text{C}$; $t_p < 200\text{ }\mu\text{s}$
Fig. 4. Output characteristics; drain current as a function of drain-source voltage; typical values



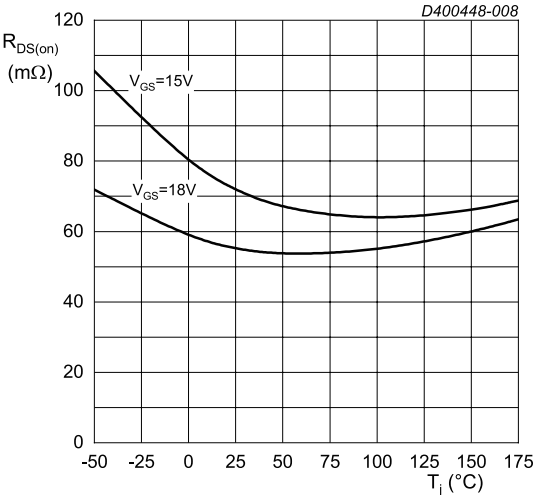
$T_j = 25\text{ }^{\circ}\text{C}$; $t_p < 200\text{ }\mu\text{s}$
Fig. 5. Output characteristics; drain current as a function of drain-source voltage; typical values



$T_j = 175\text{ }^{\circ}\text{C}$; $t_p < 200\text{ }\mu\text{s}$
Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values

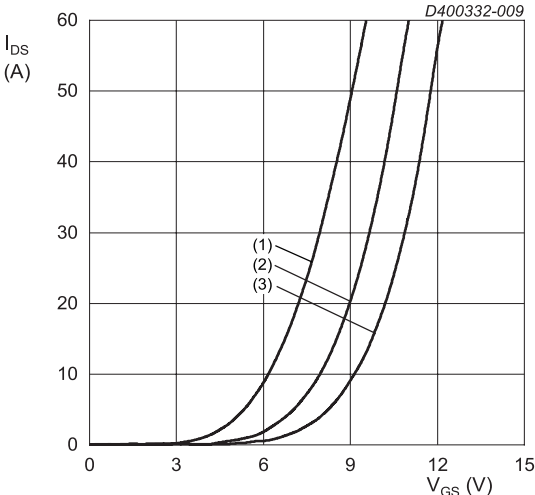


$V_{GS} = 18\text{ V}$; $t_p < 200\text{ }\mu\text{s}$
Fig. 7. Drain-source on-state resistance as a function of drain current; typical values



$I_{DS} = 15\text{ A}; t_p < 200\text{ }\mu\text{s}$

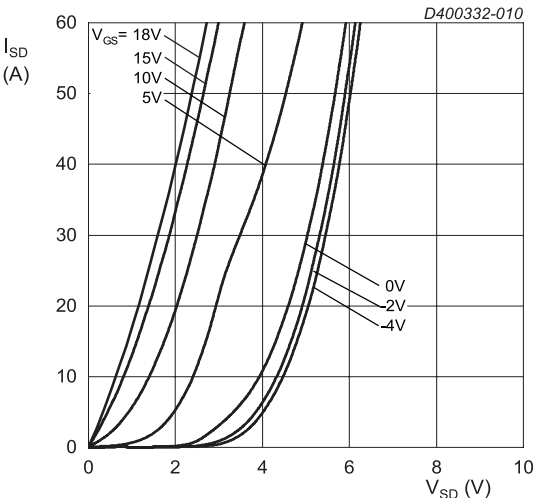
Fig. 8. Drain-source on-state resistance as a function of junction temperature



$V_{DS} = 20\text{ V}; t_p < 200\text{ }\mu\text{s}$

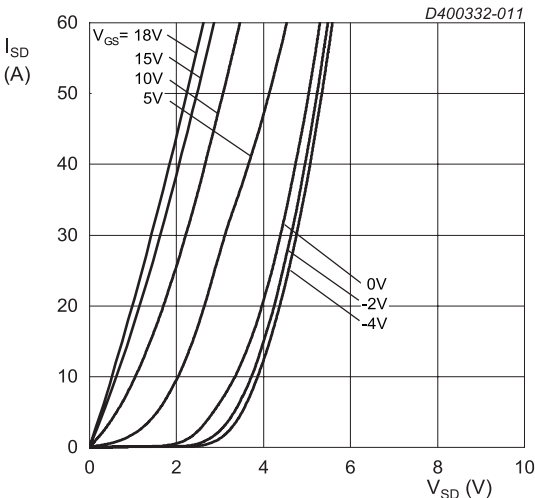
- (1) $T_j = 175\text{ }^\circ\text{C}$
- (2) $T_j = 25\text{ }^\circ\text{C}$
- (3) $T_j = -55\text{ }^\circ\text{C}$

Fig. 9. Transfer characteristics; drain current as a function of gate-source voltage; typical values



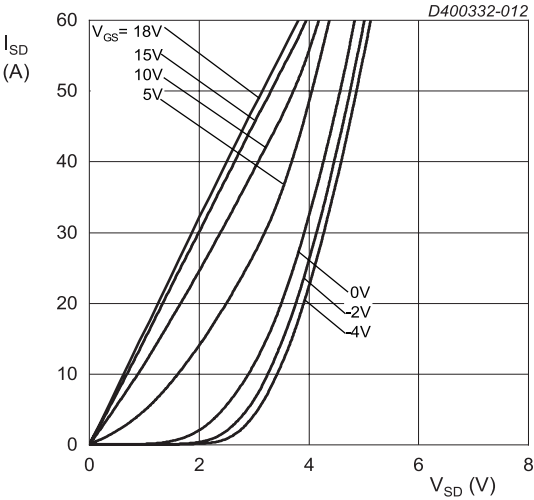
$T_j = -55\text{ }^\circ\text{C}; t_p < 200\text{ }\mu\text{s}$

Fig. 10. Body diode forward characteristics; typical values



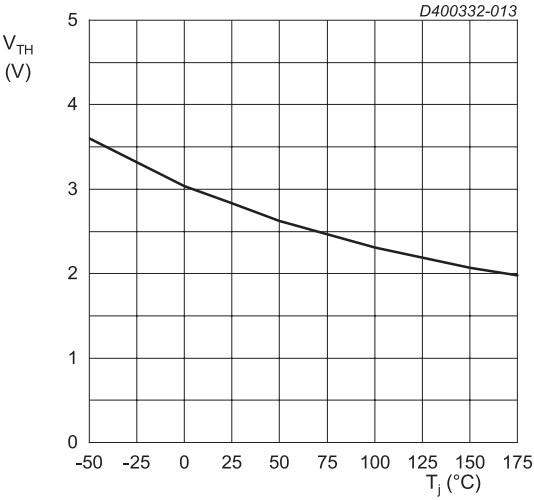
$T_j = 25\text{ }^\circ\text{C}; t_p < 200\text{ }\mu\text{s}$

Fig. 11. Body diode forward characteristics; typical values



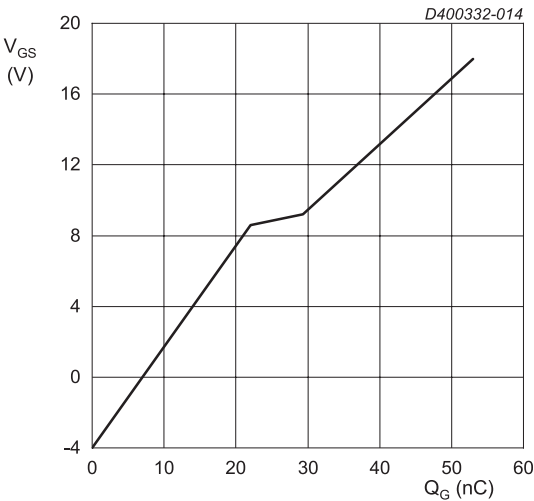
$T_j = 175\text{ }^{\circ}\text{C}$; $t_p < 200\text{ }\mu\text{s}$

Fig. 12. Body diode forward characteristics; typical values



$V_{DS} = V_{GS}$; $I_{DS} = 4\text{ mA}$

Fig. 13. Threshold voltage as a function of junction temperature



$I_{DS} = 15\text{ A}$; $I_{GS} = 0.1\text{ mA}$; $V_{DS} = 400\text{ V}$; $T_j = 25\text{ }^{\circ}\text{C}$

Fig. 14. Gate-source voltage as a function of gate charge; typical values

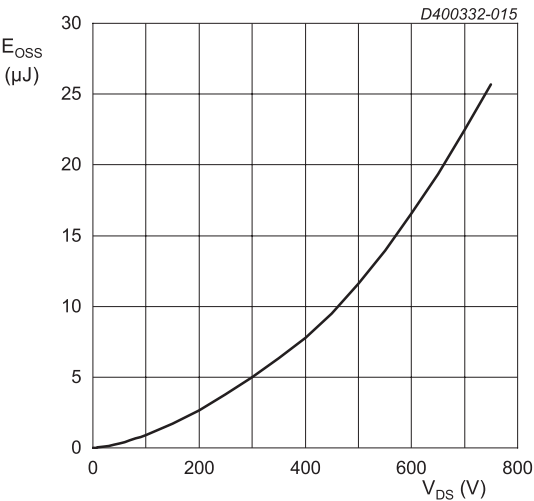
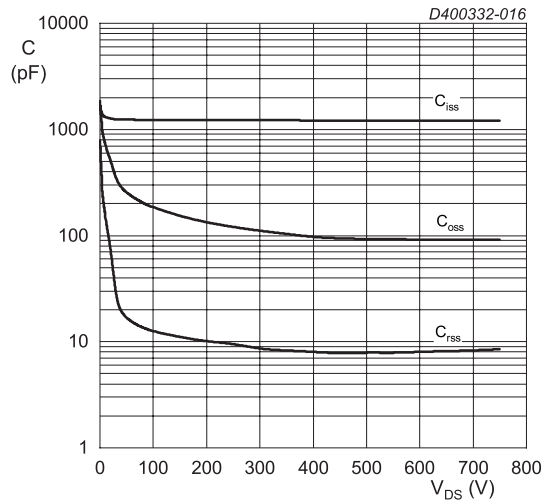
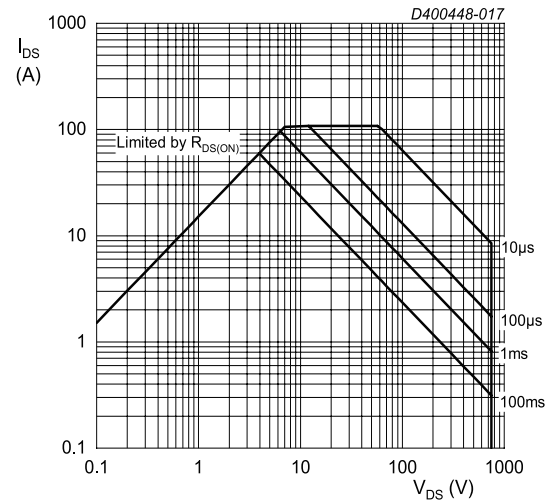


Fig. 15. Output capacitor stored energy as a function of drain-source voltage



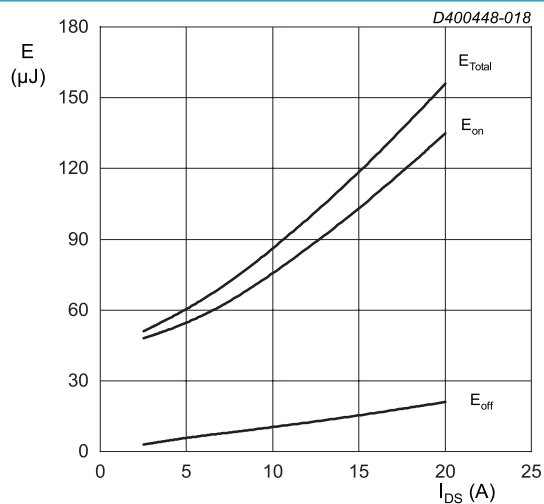
$V_{DS} = 0 - 750$ V
 $T_j = 25$ °C; $V_{AC} = 25$ mV; $f = 1$ MHz

Fig. 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



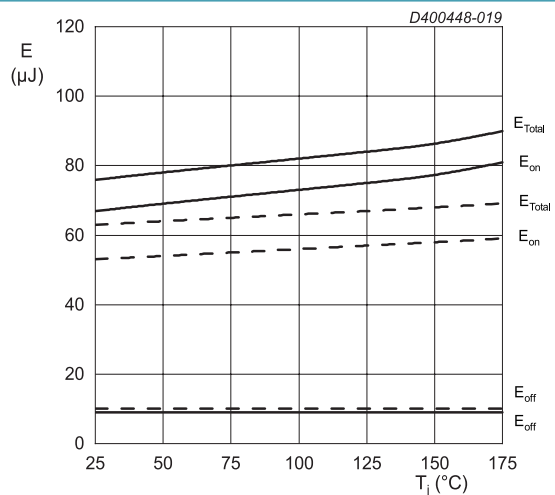
$T_j = 25$ °C; $D = 0$
 Parameter: t_p

Fig. 17. Forward bias safe operating area



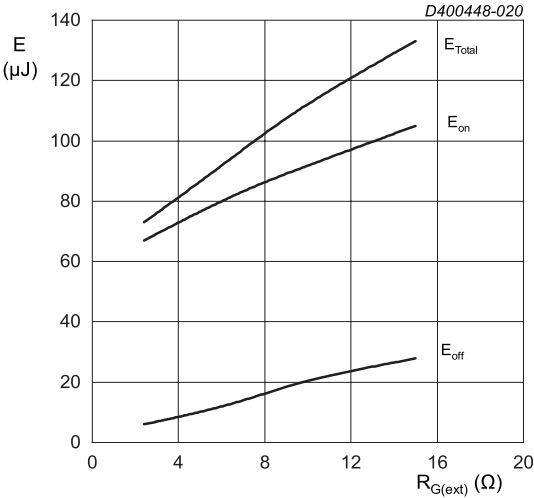
$T_j = 25$ °C; $V_{DD} = 400$ V; $R_{G(ext)} = 5.1$ Ω;
 $V_{GS} = -4$ V/18 V; $L = 100$ μH
 FWD = WNSC2M70075R-A

Fig. 18. Clamped Inductive Switching Energy as a function of drain current



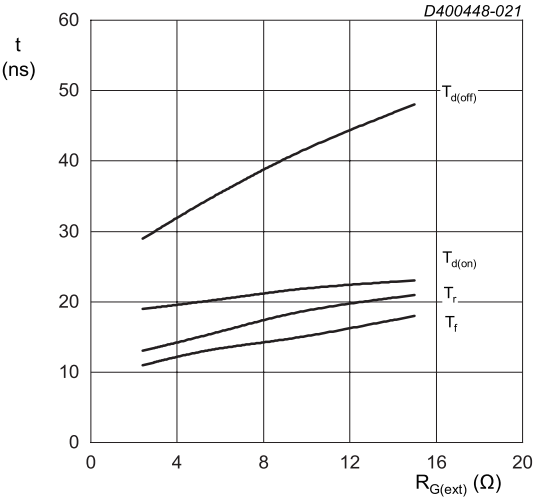
$I_{DS} = 7.5$ A; $V_{DD} = 400$ V; $R_{G(ext)} = 5.1$ Ω;
 $V_{GS} = -4$ V/18 V; $L = 100$ μH
 FWD = WNSC2M70075R-A
 FWD = WNSC6D20650W(---)

Fig. 19. Clamped Inductive Switching Energy as a function of junction temperature



$T_j = 25\text{ }^\circ\text{C}$; $V_{DD} = 400\text{ V}$; $I_{DS} = 7.5\text{ A}$; $V_{GS} = -4\text{ V}/18\text{ V}$
FWD = WNSC2M70075R-A; $L = 100\text{ }\mu\text{H}$

Fig. 20. Clamped Inductive Switching Energy as a function of external gate resistance



$T_j = 25\text{ }^\circ\text{C}$; $V_{DD} = 400\text{ V}$; $I_{DS} = 7.5\text{ A}$; $V_{GS} = -4\text{ V}/18\text{ V}$
FWD = WNSC2M70075R-A; $L = 100\text{ }\mu\text{H}$

Fig. 21. Switching time as a function of external gate resistance

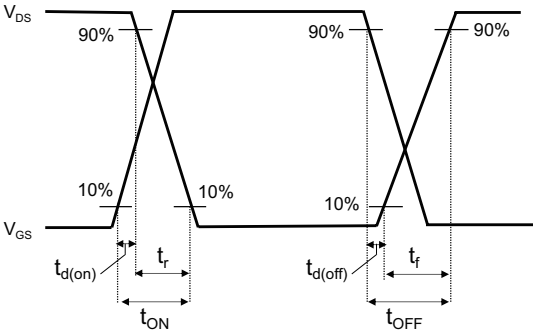
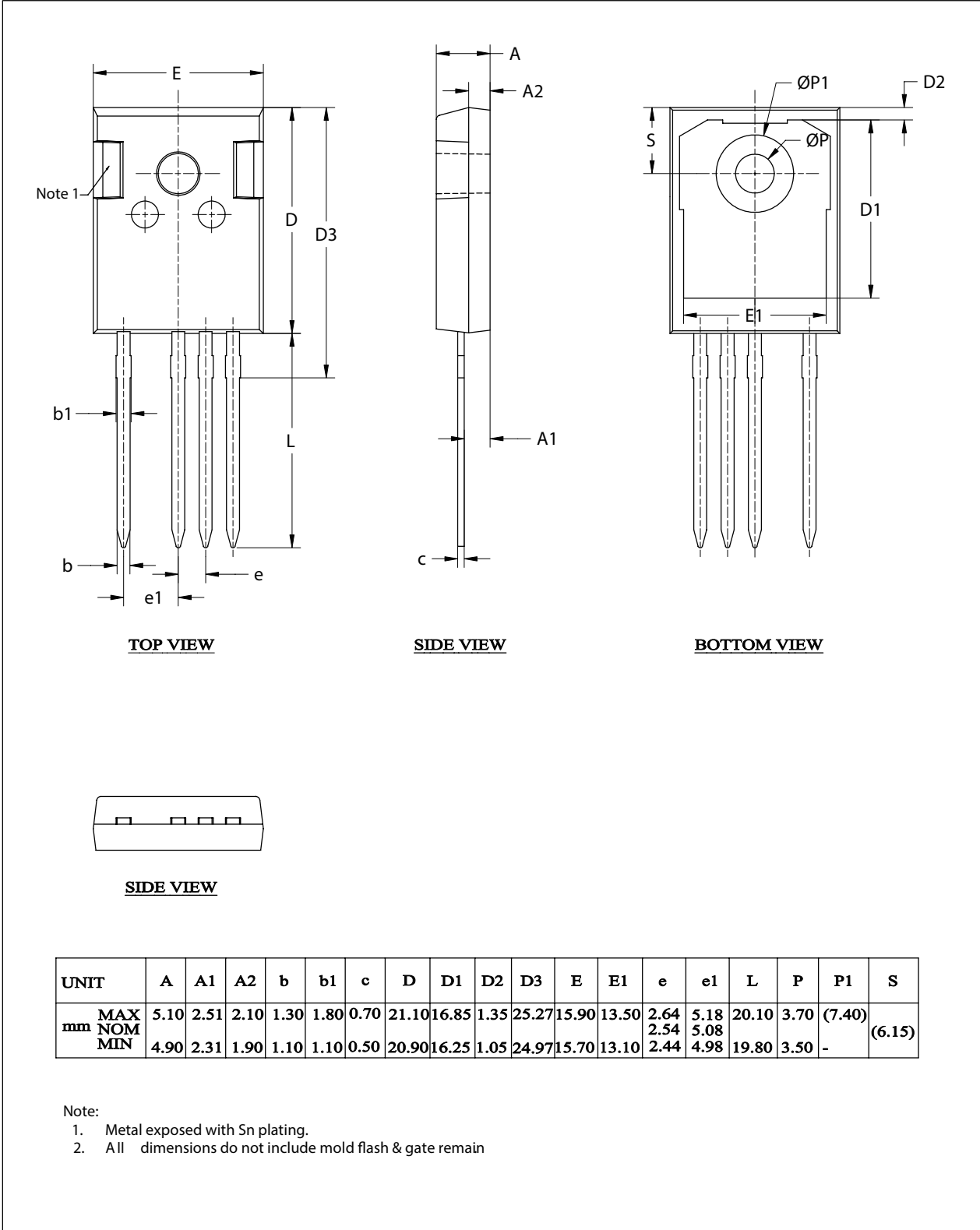


Fig. 22. Switching time definition

11. Package outline

Plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 4 leads TO-247

TO247-4L



12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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13. Contents

1. General description..... 1

2. Features and benefits 1

3. Applications 1

4. Quick reference data..... 1

5. Pinning information..... 2

6. Ordering information..... 2

7. Marking..... 2

8. Limiting values 3

9. Thermal & Mechanical characteristics 4

10. Characteristics..... 5

11. Package outline 11

12. Legal information 12

13. Contents 14

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Date of release: 11 November 2025